

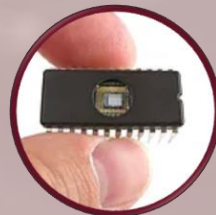


Unique one-stop-shop for the development of your custom microsystems, from design... to production

TAI PRO Engineering

- 13 Engineers and Technicians
- 120 to 150 projects per year
- Clean-room facility (ISO7)
- Production of 30 to 50k units per year

Markets



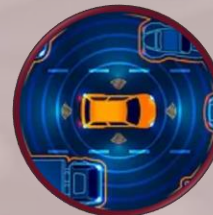
Semi-
conductors



Aeronautics



Biomedical

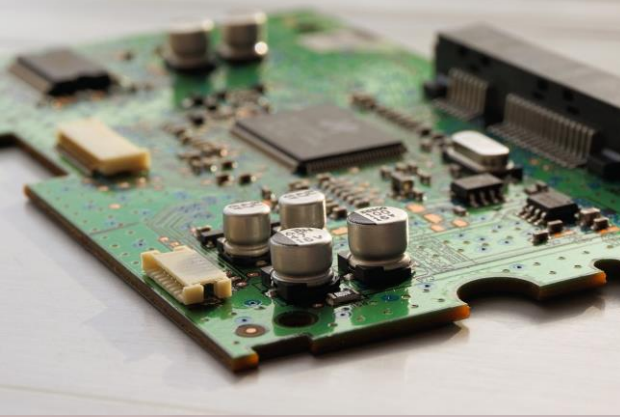


Automotive



Industry

Activities

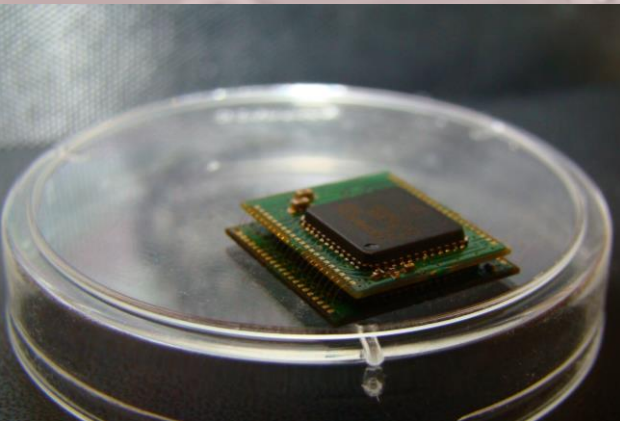
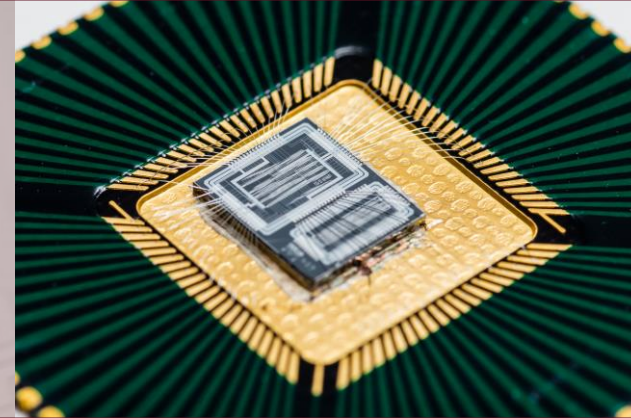


Electronic Design

- Research & European projects
- Feasibility study
- Board design & Review
- Prototyping

Production

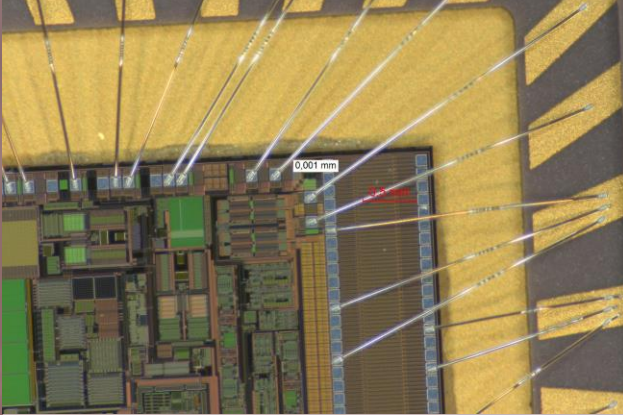
- Die bonding
- Wire bonding
- Flip-chip
- Chip-on-Board
- From prototypes to production



Turnkey projects

- One stop shop
- Hybrid electronic
- Miniaturization
- Resistance to harsh environments

Technologies

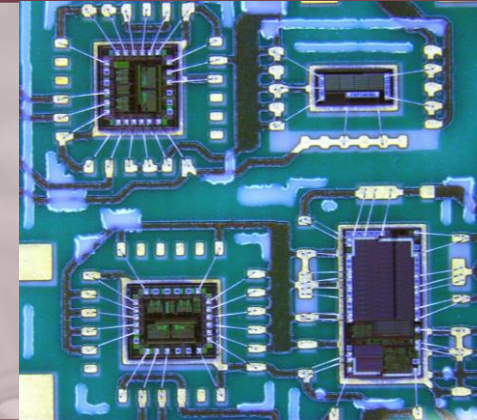


Standard Packaging

- Open cavity packages
- Ball bonding & Wedge bonding
- Encapsulation
- Laser marking

Chip-on-Board

- All type of substrates (FR4, IMS, Flex, ...)
- Ultra fine pitch wire bonding
- Heavy wire bonding
- Flip-chip
- Glob-top & Dam'n'Fill



Facilities

- Clean room class 10.000
- Automatic ball bonder & wedge bonder
- Automatic pick'n'place machine
- Heavy wire bonder
- Flip-chip machine